

REMARKS

Claims 1-24 and 34-36 were examined and rejected. Applicant amends claim 1, adds no claims, and cancels no claims. Applicant asserts that no new matter is added herein as amendment to claim 1 is supported by description of energy conduits 122-124 which may include contacts, traces, and/or energy conduit devices 142-144 (as described at paragraph 17-19, and 25, and as shown in Figures 2-3 of the Application as originally filed), such as to allow for vacuum forced attachment to a device, such as pick-and-place device (as described at paragraph 9, 15, and 28-29, and 31 of the Application as originally filed). Applicant respectfully requests reconsideration of claims 1-24 and 34-36 as amended in view of at least the following remarks.

I. Claim Objected To

The Patent Office objects to claims 8 and 20 because it is unclear which part of the “thickness” of the apparatus is referred to. In response, Applicants point out at that the “thickness” of the apparatus referred to may be a thickness such as those allowing for the functionality described in paragraphs 9 and 13-14; and shown in figures 1-3, without limitation thereto. Specifically the thickness of apparatus 110, without limitation thereto, may be a maximum thickness, such as thickness that allows closing of retainer 170 and engaging of latch 176 with lock 139 using cantilever 138 (see paragraph 9); a thickness less than the depth of socket 130, a cavity of socket 130 (see paragraph 10 and Figure 1) and less than that of socket 136 (see paragraph 10 and Figure 2); a thickness to function as a lid or cover of socket 130 (see paragraph 13) such as during transportation or shipping (see paragraphs 30-31, 34-35, and Figure 4); a thickness or depth less than or equal to a thickness or depth of an inner dimension of socket 130 or cavity thereof (see paragraph 14); and/or a thickness similar to thickness “T” as described in paragraph 14 and shown in Figure 2. Specifically, apparatus 110 may have a maximum thickness, as shown in Figure 2, that is less than or equal to the depth of the cavity of socket 130 (e.g., cavity 136 extending from the bottom inner surface of socket 130 to the topmost surface of the side walls of socket 130 on which retainer 170 is shown touching 130), without limitation thereto. However, as described above, the thickness of the apparatus is less than or equal to the depth of socket 130, and thus does not extend above the uppermost surface of the wall of socket 130 as shown in Figure 2 (e.g., does

not extend above the upper surface of the walls of socket 130, such as to prohibit retainer 170 from being locked over socket 130 and apparatus 110 by lock 139 as shown in Figures 1 and 2). Hence, for at least the reasons explained above, Applicant respectfully requests the Patent Office withdraw the objection above.

II. Claims Rejected Under 35 U.S.C. § 102

The Patent Office rejects claims 1-7 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,436,570 to Tan (Tan). It is axiomatic that for a claim to be anticipated, every limitation of that claim must be disclosed in a single reference.

Applicants respectfully disagree with the rejection above and submit that independent claim 1 is patentable over the cited reference for at least the reason that the cited reference does not teach or suggest a first side including a generally planar surface and one of contacts and traces surrounding the generally planar surfaces such that the generally planer surface is accessible to a pick-and-place vacuum force attachments, as required by claim 1.

Tan describes a test probe having a test body and test head comprising printed circuit board having a plurality of stainless steel pins embedded therein to contact socket pins of an IC socket (see Abstract; and col. 2, lines 48 through col. 3, lines 20). Specifically, Tan teaches testing end 5 of probe body 20 comprising a plurality of slots 23 for accommodating cable connection header 10 (see col. 3, lines 40-52). According to Tan, first, a test probe is coupled electrically to test equipment; second, an IC device is removed from an IC socket; and then, the test probe takes the place of the IC device in the socket (see col. 1, lines 15-26).

Consequently, the Patent Office has not identified and Applicants are unable to find any teaching or suggestion of a generally planar surface adapted to be attached to via a vacuum force attachment, as required by claim 1. Specifically, Tan teaches slots 23 and cable connection header 10 (see Fig. 3). Thus, terminals 4, slots 23, nor header 10 (e.g., see Tan Figure 3) disclose a planar surface and contacts were traces as required by claim 1. Moreover, a practitioner in the art would not be motivated to consider contacts

or traces surrounding a generally planar surface such that the generally planar surface is accessible to a pick-and-place vacuum force attachment, upon consideration of the above described structure of Tan by that practitioner because Tan teaches header 10 as the attachment to body 20 (see Tan Fig. 3). Hence, for at least the reasons above, Applicants respectfully request the Patent Office withdraw the rejection above.

Applicants submit that dependent claims 2-7, being dependent upon allowable base claim 1, are patentable over the cited references for at least the reasons cited above. Thus, Applicants respectfully request the Patent Office withdraw the rejection of dependent claims 2-7.

III. Claims Rejected Under 35 USC § 112

The Patent Office rejects claims 8-24 and 34-36 under 35 USC § 112, first paragraph as failing to comply with the written description requirement because it appears that the original specification does not have support for “a thickness less than or equal to a depth of the cavity” as claimed in claims 8 and 20, or “a thickness to allow a retainer of the socket to close over the apparatus” as claimed in claims 34-36.

Applicant respectfully disagree since apparatus 112 having a thickness less than or equal to a depth of socket 130, or a thickness to allow retainer 170 to close over socket 130 is clearly shown and described, as noted above, in the application as originally filed. For instance, without limitation thereto, a sectional side view through line A-A' is shown in Figure 2 of Applicant's application as filed where apparatus 110 has a total thickness less than or equal to that of cavity 136; and apparatus 110 having a thickness to allow retainer 170 to close over apparatus 110 so that lock 139 may engage latch 176 is shown in Figure 1 of Applicant's application as filed. However, an apparatus such as probe body 20 of Tan clearly has a thickness much greater than that claimed, (see Figure 4 of Tan). Hence, Applicant respectfully requests the Patent Office withdraw the rejection above, and encourages the Patent Office to find an appropriate reference.

CONCLUSION

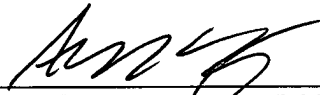
In view of the foregoing, it is believed that all claims now pending patentably define the subject invention over the prior art of record and are in condition for allowance, and such action is earnestly solicited at the earliest possible date.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2666 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17. If a telephone interview would expedite the prosecution of this Application, the Examiner is invited to contact the undersigned at (310) 207-3800.

Respectfully submitted,

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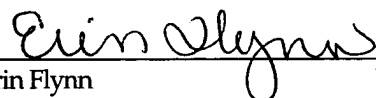
Dated: December 29, 2005

By: 
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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on July 19, 2005.


Erin Flynn December 29, 2005